



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-09
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	YMYG*UP79J51	A	SA1A	2015-06-09
Amount	UoM	Unit type	ST ECOPACK Grade	
24.4	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMD	3-3-0.95	6	No lead	
Comment	Package: VFDFPN 6 3X3 0,95 PITCH; MDF valid for ST1L05CPU33R			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	YMYG*UP79J51						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Silicon die	Other inorganic materials	0.428	mg	supplier	Die	Silicon (Si)	7440-21-3		0.398	mg	929907	16311	
Silicon die				supplier	metallization	Aluminum (Al)	7429-90-5		0.006	mg	14019	246	
Silicon die				supplier	metallization	Titanium Nitride (TiN)	25583-20-4		0.003	mg	7009	123	
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.005	mg	11682	205	
Silicon die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	2336	41	
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.01	mg	23364	410	
Silicon die				supplier	passivation	Gamma-butyrolactone	96-48-0		0.003	mg	7009	123	
Silicon die				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	4673	82	
Leadframe	Copper & its alloys	8.952	mg	SUPPLIER	Alloy	Copper (Cu)	7440-50-8		8.646	mg	965818	354344	
Leadframe				SUPPLIER	Alloy	Iron (Fe)	7439-89-6		0.202	mg	22565	8279	
Leadframe				SUPPLIER	Alloy	Lead (Pb)	7439-92-1		0.001	mg	112	41	
Leadframe				SUPPLIER	Alloy	Iron Phosphide (Fe2P)	1310-43-6		0.002	mg	223	82	
Leadframe				SUPPLIER	Alloy	Zinc (Zn)	7440-66-6		0.011	mg	1229	451	
Leadframe				SUPPLIER	Alloy	Silver (Ag)	7440-22-4		0.09	mg	10054	3689	
Die attach	Other organic materials	0.096	mg	SUPPLIER	Epoxy	Silver (Ag)	7440-22-4		0.066	mg	687500	2705	
Die attach				SUPPLIER	Epoxy	methylene diacrylate	42594-17-2		0.024	mg	250000	984	
Die attach				SUPPLIER	Epoxy	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.003	mg	31250	123	
Die attach				SUPPLIER	Epoxy	Polymer of Polybutadiene + Anhydride	Proprietary		0.003	mg	31250	123	
Bonding wire	Other inorganic materials	0.086	mg	SUPPLIER	Bonding Wire	Copper (Cu)	7440-50-8		0.084	mg	976744	3443	
Bonding wire				SUPPLIER	Bonding Wire	Palladium (Pd)	7440-05-3		0.002	mg	23256	82	
Encapsulation	Other organic materials	14.631	mg	SUPPLIER	molding compound	Silica Fused	60676-86-0		13.711	mg	937120	561926	
Encapsulation				SUPPLIER	molding compound	Epoxy Resin	25068-38-6		0.438	mg	29936	17951	
Encapsulation				SUPPLIER	molding compound	Phenol Resin	29690-82-2		0.439	mg	30005	17992	
Encapsulation				SUPPLIER	molding compound	Carbon Black	1333-86-4		0.043	mg	2939	1762	
Finishing	Other inorganic materials	0.207	mg	SUPPLIER	Connection coating	Tin (Sn)	7440-31-5		0.207	mg	1000000	8484	